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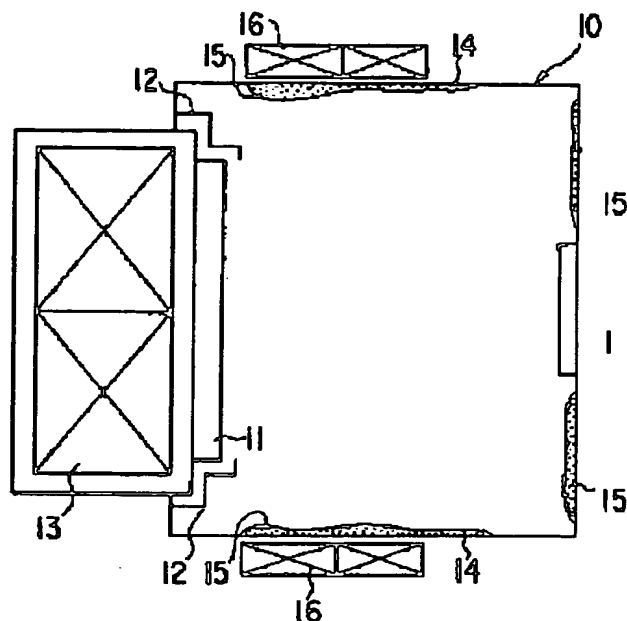
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APPLICANT : TOSHIBA CORP;

INVENTOR : IGUCHI TOMOYUKI;

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TITLE : PRODUCTION OF SEMICONDUCTOR
DEVICE AND APPARATUS FOR
PRODUCING SEMICONDUCTOR
DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To prevent the occurrence of short circuit between cathode chambers caused by the adhesion of peeled pieces to a magnetic material target and the peeled pieces by suppressing the peeling of magnetic material films adhered to sputtered film stick-proof plates at the time of sputtering with a magnetic material film sputtering apparatus.

SOLUTION: This apparatus includes a chamber 10 for sputtering, the magnetic material target 11 which is disposed to face the disposition part of a semiconductor wafer 1 on the inner side of the chamber, a magnet 13 which is disposed on the rear side of the target on the outer side of the chamber, a pair of the sputtered film stick-proof plates 14 which are disposed on the opposite wall surface parts in the direction orthogonal with the opposite directions of the wafer target among the inside wall surfaces of the chamber and magnets 16 for preventing the peeling of the sputtered films disposed around the space between the wafer targets on the outer side of the chamber.

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